# **MA6J786X**

Silicon epitaxial planar type

For high speed switching circuits

#### Overview

MA6J786X is optimal for general circuit supplies. The assembly of 3 MA3X786 elements in parallel in one package.

#### Features

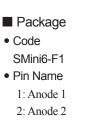
- Forward current (Average)  $I_{F(AV)} = 100$  mA rectification is possible
- $\bullet$  Short reverse recovery time  $t_{\rm rr}$  , optimum for high-frequency rectification
- $\bullet$  Low forward voltage  $V_{\rm F}$  and good rectification efficiency

#### ■ Absolute Maximum Ratings T<sub>a</sub> = 25°C

Parameter	Symbol	Rating	Unit	
Reverse voltage	V <sub>R</sub>	30	V	
Maximum peak reverse voltage	V <sub>RM</sub>	30	V	
Forward current (Average)	I <sub>F(AV)</sub>	100	mA	
Peak forward current	I <sub>FM</sub>	300	mA	
Non-repetitive peak forward surge current *	I <sub>FSM</sub>	1	А	
Junction temperature	T <sub>j</sub> 125		°C	
Storage temperature	T <sub>stg</sub>	-55 to +125	°C	

Note) \*: 50 Hz sine wave 1 cycle (Non-repetitive peak current)

#### Electrical Characteristics $T_a = 25^{\circ}C \pm 3^{\circ}C$

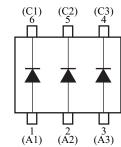


3: Anode 3

4: Cathode 3 5: Cathode 2 6: Cathode 1

Marking Symbol: M8B



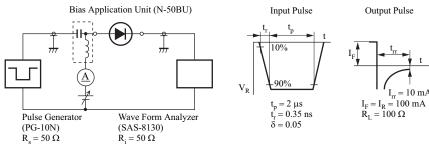


Parameter	Symbol	Conditions	Min	Тур	Max	Unit
Forward voltage	$V_{F1}$	$I_F = 100 \text{ mA}$			0.55	V
Reverse current	I <sub>R</sub>	$V_R = 30 V$			15	μΑ
Terminal capacitance	Ct	$V_R = 0$ , f = 1 MHz		20		pF
Reverse recovery time *	t <sub>rr</sub>	$\begin{split} I_F = I_R = 100 \text{ mA}, & I_{rr} = 0.1 \times I_R \text{ ,} \\ R_L = 100 \ \Omega \end{split}$		1.0		ns

Note) 1. Measuring methods are based on JAPANESE INDUSTRIAL STANDARD JIS C 7031 measuring methods for diodes.

2. This product is sensitive to electric shock (static electricity, etc.). Due attention must be paid on the charge of a human body and the leakage of current from the operating equipment.

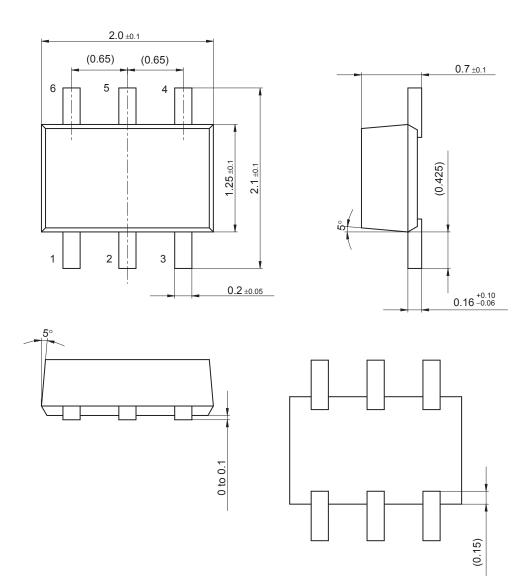
3. \*: t<sub>rr</sub> measurement circuit



### **Panasonic**

### SMini6-F1

Unit: mm



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